

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-070my 330x490mm	50200246	70	VS	1	
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...	50202996	98		2	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B(...	50203000	0		3	
		70	L2		
B-RS-FR4-ML-0.107mm-070+070-TG150-HF-...	50203106	107		4	A01
		70	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B(...	50203000	55		5	
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...	50202996	33		6	B00
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B(...	50203000	55		7	
		70	L4		
B-RS-FR4-ML-0.107mm-070+070-TG150-HF-...	50203106	107		8	A02
		70	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B(...	50203000	98		9	
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...	50202996	0		10	
A-RS Kupferfolie-070my 330x490mm	50200246	70	RS	11	

Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

973 µm

Version 1.2.20.35

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